Ver 1.00

2024-06-20

The latest support list download from: https://redmine.rock-chips.com/documents/50

• Symbol

Symbol	Description
√	Fully Tested , Applicable and Mass Production
T/A	Fully Tested , Applicable and Ready for Mass Production
S/A	The Samples have Passed the Reliability Test. However, the Platform Compatibility Test was also required before Mass Production.
D/A	Datasheet Applicable, Need Sample to Test.
N/A	Not Applicable

• Note

• Revision History

Revision No.	History	Date
1.05	1. Add RK3576 2. Add THGJFGT2T85BAB5, THGJFGT1T45BAB8, THGJFGT0T25BAB8, THGJFGG9T15BAB8, THGJFGT1E45BAIL, THGJFGT2T85BAIR, MTFC64GAZAOTD-AIT, MTFC128GAZAOTD-AIT, MTFC256GAZAOTD-AIT, MTFC128GBCAVHF-WT, KLUDG4UHGC-B0E1, KLUCG2U1DC-B0F1, KLUDG2R1DE-B0F1, KLUEG4R1DE-B0F1, KLUCG4J1ZD-C0CQ, KLUDG8J1ZD-C0CQ, KLUDG4UHYB-B0EQ, KLUEG8UHYB-B0EQ, YMUS8B4TF1D1C1, YMUS9B4TF2D1C1, YMUSAB4TF3D1C1, YMUS7B2TE1A2C1, YMUS8B2TE2A2C1, YMUS9B2TE3A2C1, BWU3AKC26C128G, BWU3AKC46C256G, FEUDME064G-B8A19, FEUDME128G-B8A19, FEUDME256G-C8H09, FEUDNN064G-C2G07-P, FEUDNN128G-C2G07-P, FEUDNN256G-C2G07-O, BWU2A0526B128G, BWU2A0516B064G and HBE3-1280CHAA.	2024.06.20

Manufacturer	Part Number	Device Size (bits)	Byte Size	Process	Version	VCC (V)	VCCQ (V)	VCCQ2 (V)	Temp. (°C)	RK3576		Rema	rk
KIOXIA	THGJFGT2T85BAB5	512Gb TLC x 8	512GB	3D	3.1	2.5/3.3	1.2	-	-40/105	D/A		AUTO	
KIOXIA	THGJFGT1T45BAB8	512Gb TLC x 4	256GB	3D	3.1	2.5/3.3	1.2	-	-40/105	D/A		AUTO	
KIOXIA	THGJFGT0T25BAB8	512Gb TLC x 2	128GB	3D	3.1	2.5/3.3	1.2	-	-40/105	D/A		AUTO	
KIOXIA	THGJFGG9T15BAB8	512Gb TLC x 1	64GB	3D	3.1	2.5/3.3	1.2	-	-40/105	D/A		AUTO	
KIOXIA	THGJFGT1E45BAIL	512Gb TLC x 4	256GB	3D	3.1	2.5/3.3	1.2	-	-25/85	D/A			
KIOXIA	THGJFGT2T85BAIR	512Gb TLC x 8	512GB	3D	3.1	2.5/3.3	1.2	-	-25/85	D/A			

Manufacturer	Part Number	Device Size (bits)	Byte Size	Process	Version	VCC (V)	VCCQ (V)	VCCQ2 (V)	Temp. (°C)	RK3576		Rema	ırk
MICRON	MTFC64GAZAOTD-AIT	256Gb TLC x 2	64GB	3D	2.1	3.3	-	1.8	-40/105	D/A		AUTO	
MICRON	MTFC128GAZAOTD-AIT	256Gb TLC x 4	128GB	3D	2.1	3.3	-	1.8	-40/105	D/A		AUTO	
MICRON	MTFC256GAZAOTD-AIT	256Gb TLC x 8	256GB	3D	2.1	3.3	-	1.8	-40/105	D/A		AUTO	
MICRON	MTFC128GBCAVHF-WT	512Gb TLC x 2	128GB	3D	3.1	2.5	1.2	-	-25/85	D/A			

Manufacturer	Part Number	Device Size (bits)	Byte Size	Process	Version	VCC (V)	VCCQ (V)	VCCQ2 (V)	Temp. (°C)	RK3576		Rema	rk
SAMSUNG	KLUDG4UHGC-B0E1	512Gb TLC x 2	128GB	3D	3.1	2.5	1.2	-	-25/85	D/A			
SAMSUNG	KLUCG2U1DC-B0F1	512Gb TLC x 1	64GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
SAMSUNG	KLUDG2R1DE-B0F1	512Gb TLC x 2	128GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
SAMSUNG	KLUEG4R1DE-B0F1	512Gb TLC x 4	256GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
SAMSUNG	KLUCG4J1ZD-C0CQ	128Gb MLC x 4	64GB	2D	2.1	3.3	-	1.8	-40/105	D/A		AUTO	
SAMSUNG	KLUDG8J1ZD-C0CQ	128Gb MLC x 8	128GB	2D	2.1	3.3	-	1.8	-40/105	D/A		AUTO	
SAMSUNG	KLUDG4UHYB-B0EQ	256Gb TLC x 4	128GB	3D	3.1	2.5	1.2	_	-40/105	D/A		AUTO	
SAMSUNG	KLUEG8UHYB-B0EQ	256Gb TLC 8 4	256GB	3D	3.1	2.5	1.2	-	-40/105	D/A		AUTO	
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Manufacturer	Part Number	Device Size (bits)	Byte Size	Process	Version	VCC (V)	VCCQ (V)	VCCQ2 (V)	Temp. (°C)	RK3576		Rema	rk
YMTC	YMUS8B4TF1D1C1	512Gb TLC x 2	128GB	3D	3.1	2.5	1.2	-	-25/85	D/A			
YMTC	YMUS9B4TF2D1C1	512Gb TLC x 4	256GB	3D	3.1	2.5	1.2	-	-25/85	D/A			
YMTC	YMUSAB4TF3D1C1	512Gb TLC x 8	512GB	3D	3.1	2.5	1.2	-	-25/85	D/A			
YMTC	YMUS7B2TE1A2C1	512Gb TLC x 1	64GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
YMTC	YMUS8B2TE2A2C1	512Gb TLC x 2	128GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
YMTC	YMUS9B2TE3A2C1	512Gb TLC x 4	256GB	3D	2.2	3.3	-	1.8	-25/85	D/A			

Manufacturer	Part Number	Device Size (bits)	Byte Size	Process	Version	VCC (V)	VCCQ (V)	VCCQ2 (V)	Temp. (°C)	RK3576		Rema	rk
BIWIN	BWU3AKC26C128G	512Gb TLC x 2	128GB	3D	3.1	2.5	1.2	-	-25/85	D/A			
BIWIN	BWU3AKC46C256G	512Gb TLC x 4	256GB	3D	3.1	2.5	1.2	-	-25/85	D/A			
BIWIN	BWU2A0526B128G	512Gb TLC x 2	128GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
BIWIN	BWU2A0516B064G	512Gb TLC x 1	64GB	3D	2.2	3.3	-	1.8	-25/85	D/A			

Manufacturer	Part Number	Device Size (bits)	Byte Size	Process	Version	VCC (V)	VCCQ (V)	VCCQ2 (V)	Temp. (°C)	RK3576		Rema	rk
FORESEE	FEUDME064G-B8A19	512Gb TLC x 1	64GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
FORESEE	FEUDME128G-B8A19	512Gb TLC x 2	128GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
FORESEE	FEUDME256G-C8H09	512Gb TLC x 4	256GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
FORESEE	FEUDNN064G-C2G07-P	512Gb TLC x 1	64GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
FORESEE	FEUDNN128G-C2G07-P	512Gb TLC x 2	128GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
FORESEE	FEUDNN256G-C2G07-O	512Gb TLC x 4	256GB	3D	2.2	3.3	-	1.8	-25/85	D/A			
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Manufacturer	Part Number	Device Size (bits)	Byte Size	Process	Version	VCC (V)	VCCQ (V)	VCCQ2 (V)	Temp. (°C)	RK3576		Rema	rk
HOSIN	HBE3-1280CHAA	512Gb TLC x 2	128GB	3D	2.2	3.3	-	1.8	-25/85	D/A			